HOLT PLASTIC PACKAGE PROCESS OPTIONS

I = Industrial Grade (-40°C to +85°C)
T = High Temp Grade (-55 °C to +125°C)
M = Military Grade (-55°C to +125°C)

PROCESS STEP	PROCESS FLOW			COMMENTS
	I	**T**	**M**	
INCOMING WAFER INSPECTION	**X**	**X**	**X**	PARAMETRICS, DIE VISUAL
WAFER PROBE	**100%**	**100%**	**100%**	
SAW	**X**	**X**	**X**	
DIE VISUAL INSPECTION	**100%**	**100%**	**100%**	MIL-STD-883, METHOD 2010, CONDITION B
DIE ATTACH	**X**	**X**	**X**	EPOXY
WIRE BOND	**X**	**X**	**X**	GOLD WIRE
MOLD	**X**	**X**	**X**	
MARK & CURE	**X**	**X**	**X**	
TRIM & FORM	**X**	**X**	**X**	
LEAD FINISH	**X**	**X**	**X**	SOLDER PLATE
ELECTRICAL TEST @ ROOM	**100%**	**100%**	**100%**	
ELECTRICAL TEST @ HOT TEMPERATURE	**SAMPLE (85°C)**	**100% (125°C)**	**SAMPLE (125°C)**	MILITARY GRADE PRODUCT 100% TEMPERATURE TEST AFTER BURN-IN
ELECTRICAL TEST @ COLD TEMPERATURE	**SAMPLE (-40°C)**	**100% (-55°C)**	**SAMPLE (-55°C)**	
BURN-IN			**100%**	160 HOURS, MIL-STD-883, METHOD 1015
POST BURN-IN ELECTRICAL			**100%**	@ 25°C, 5% PDA
FINAL ELECTRICAL TEST			**100%**	@ -55°C & +125°C
GROUP ‘A“ ELECTRICAL TEST			**X**	MIL-STD-883, METHOD 5005
SOLDERABILITY			**X**	MIL-STD-883, METHOD 2003
EXTERNAL VISUAL	**X**	**X**	**X**	
BAKE & DRY PACK	**X**	**X**	**X**	
QC PLANT CLEARANCE	**X**	**X**	**X**	
PACK & SHIP	**X**	**X**	**X**	